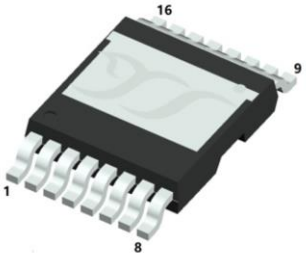
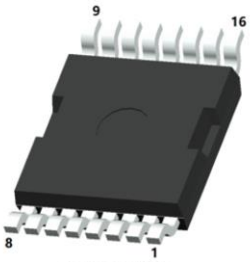
# N-Channel Enhancement Mode Field Effect Transistor

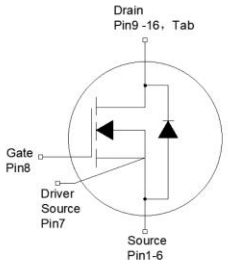



Top View




Bottom View

TOLT




## Product Summary

- $V_{DS}$ 100V
- $I_D$ 340A
- $R_{DS(ON)}$( at $V_{GS}$=10V) ＜1.7mΩ
- 100% EAS Tested
- 100% ▽$V_{DS}$ Tested

## General Description

- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

## Applications

- High power inverter system
- BMS appliances

## ■ Absolute Maximum Ratings ($T_J$=25℃ unless otherwise noted)

| Parameter | | | Symbol | Limit | Unit |
|---|---|---|---|---|---|
| Drain-source Voltage | | | $V_{DS}$ | 100 | V |
| Gate-source Voltage | | | $V_{GS}$ | ±20 | V |
| Continuous Drain Current (Note 1,2 ) | Steady-State | $T_A$=25℃ , $V_{GS}$= 10V | $I_D$ | 34 | A |
| | | $T_A$=100℃, $V_{GS}$= 10V | | 24 | |
| Continuous Drain Current (Note 1,3 ) | Steady-State | $T_C$=25℃, $V_{GS}$= 10V | | 340 | |
| | | $T_C$ =100℃, $V_{GS}$= 10V | | 240 | |
| Pulsed Drain Current | $T_C$=25℃, $t_p$=100μs | | $I_{DM}$ | 1360 | A |
| Avalanche energy | $V_G$=10V, $R_G$=25Ω, L=5mH, IAS=33A | | EAS | 2722.5 | mJ |
| Total Power Dissipation (Note 1,2) | Steady-State | $T_A$=25℃ | $P_D$ | 4.1 | W |
| | | $T_A$=100℃ | | 2 | |
| Total Power Dissipation (Note 1,3 ) | Steady-State | $T_C$=25℃ | | 416 | |
| | | $T_C$ =100℃ | | 208 | |
| Junction and Storage Temperature Range | | | $T_J$ ,$T_{STG}$ | -55～+175 | ℃ |

## ■Thermal resistance

| Parameter | | Symbol | Typ | Max | Units |
|---|---|---|---|---|---|
| Thermal Resistance Junction-to-Ambient (Note 2) | Steady-State | $R_{\theta JA}$ | 30 | 36 | ℃/W |
| Thermal Resistance Junction-to-Case | Steady-State | $R_{\theta JC}$ | 0.3 | 0.36 | |

## ■ Ordering Information (Example)

| PREFERED P/N | PACKING CODE | Marking | MINIMUM PACKAGE(pcs) | INNER BOX QUANTITY(pcs) | OUTER CARTON QUANTITY(pcs) | DELIVERY MODE |
|---|---|---|---|---|---|---|
| YJTL1D7G10H | F1 | YJTL1D7G10H | 1200 | 1200 | 6000 | 13” reel |

## ■ Electrical Characteristics ($T_J$=25℃ unless otherwise noted)

| Parameter | Symbol | Conditions | Min | Typ | Max | Units |
|---|---|---|---|---|---|---|
| **Static Parameter** | | | | | | |
| Drain-Source Breakdown Voltage | $BV_{DSS}$ | $V_{GS}$= 0V, $I_D$=250μA | 100 | - | - | V |
| | | $V_{GS}$= 0V, $I_D$=10mA | 100 | - | - | V |
| Zero Gate Voltage Drain Current | $I_{DSS}$ | $V_{DS}$=80V, $V_{GS}$=0V | - | - | 1 | μA |
| | | $V_{DS}$=80V, $V_{GS}$=0 V, Tj=125℃ | - | - | 100 | μA |
| Gate-Body Leakage Current | $I_{GSS}$ | $V_{GS}$= ±20V, $V_{DS}$=0V | - | - | ±100 | nA |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS}$= $V_{GS}$, $I_D$=250μA | 2 | 2.6 | 4 | V |
| Static Drain-Source On-Resistance | $R_{DS(ON)}$ | $V_{GS}$=10V, $I_D$=20A | - | 1.28 | 1.7 | mΩ |
| Diode Forward Voltage | $V_{SD}$ | $I_S$=20A, $V_{GS}$=0V | - | 0.75 | 1.2 | V |
| Gate resistance | $R_G$ | f=1MHz | - | 1.45 | - | Ω |
| Maximum Body-Diode Continuous Current | $I_S$ | | - | - | 285 | A |
| **Dynamic Parameters** | | | | | | |
| Input Capacitance | $C_{iss}$ | $V_{DS}$=50V, $V_{GS}$=0V, f=1MHz | - | 10700 | - | pF |
| Output Capacitance | $C_{oss}$ | | - | 2010 | - | |
| Reverse Transfer Capacitance | $C_{rss}$ | | - | 35 | - | |
| **Switching Parameters** | | | | | | |
| Total Gate Charge | $Q_g$ | $V_{GS}$=10V, $V_{DS}$=50V, $I_D$=30A | - | 166 | - | nC |
| Gate-Source Charge | $Q_{gs}$ | | - | 34 | - | |
| Gate-Drain Charge | $Q_{gd}$ | | - | 49 | - | |
| Reverse Recovery Charge | $Q_{rr}$ | $I_F$=30A, di/dt=100A/us | - | 167 | - | nC |
| Reverse Recovery Time | $t_{rr}$ | | - | 92 | - | ns |
| Turn-on Delay Time | $t_{D(on)}$ | $V_{GS}$=10V, $V_{DD}$=50V, $I_D$=30A $R_{GEN}$=4.5Ω | - | 30 | - | ns |
| Turn-on Rise Time | $t_r$ | | - | 65 | - | |
| Turn-off Delay Time | $t_{D(off)}$ | | - | 121 | - | |
| Turn-off fall Time | $t_f$ | | - | 107 | - | |

Note:

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
2. The value of $R_{\theta JA}$ is measured with the device mounted on the 40mm*40mm*1.1mm single layer FR-4 PCB board with 1 $in^2$ pad of 2oz. Copper, in the still air environment with TA =25℃.The maximum allowed junction temperature of 175℃. The value in any given application depends on the user's specific board design.
3. Thermal resistance from junction to soldering point (on the exposed drain pad).

## ■Typical Electrical and Thermal Characteristics Diagrams

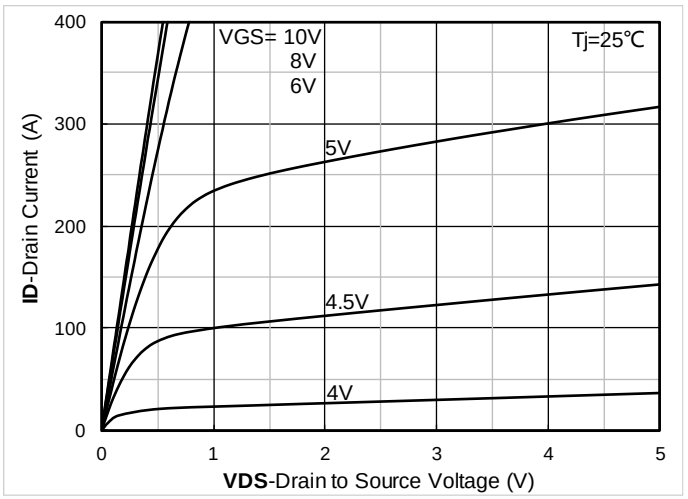



Figure 1. Output Characteristics

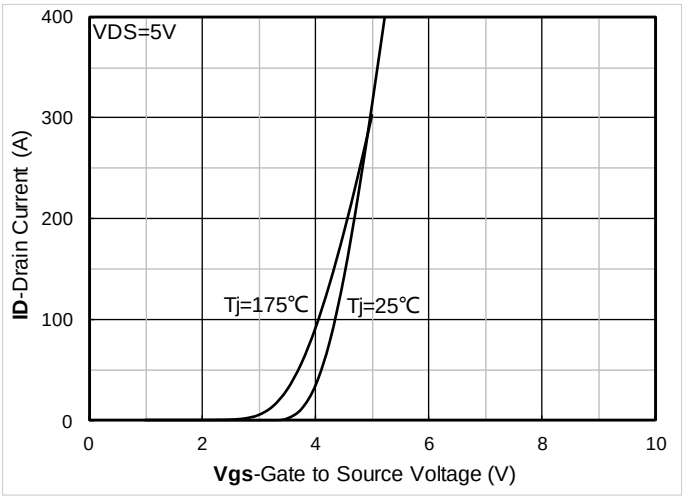



Figure 2. Transfer Characteristics

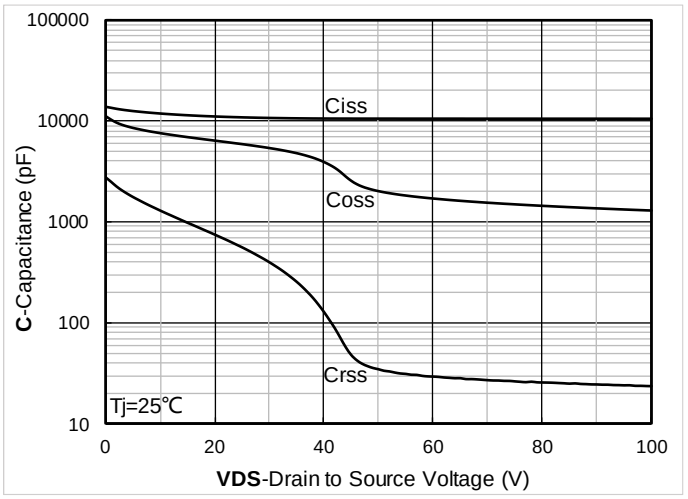



Figure 3. Capacitance Characteristics

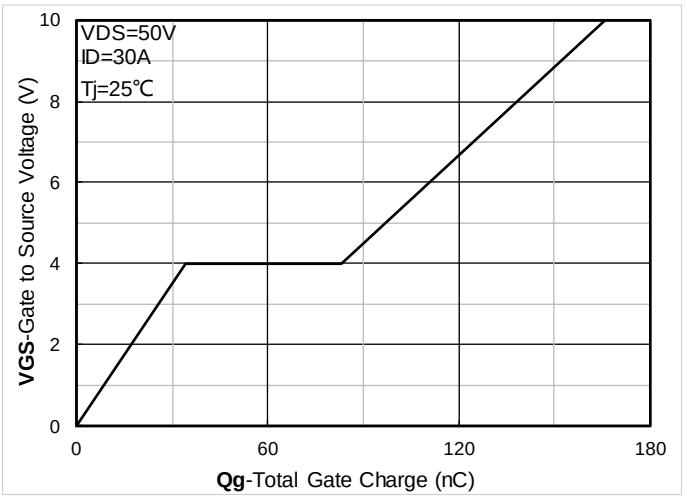



Figure 4. Gate Charge

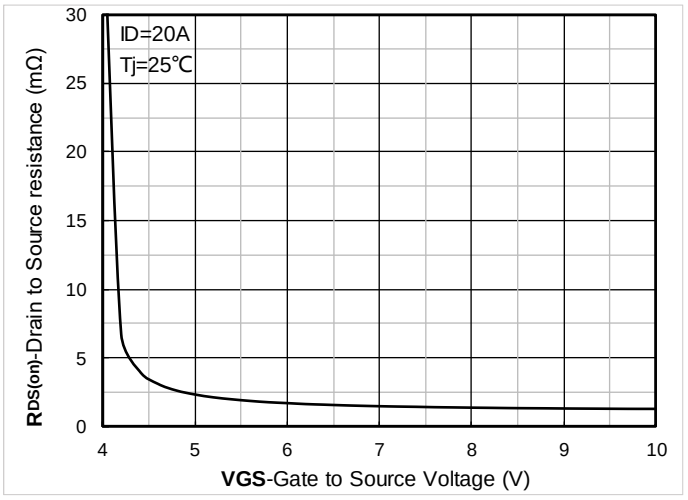



Figure 5. On-Resistance vs Gate to Source Voltage

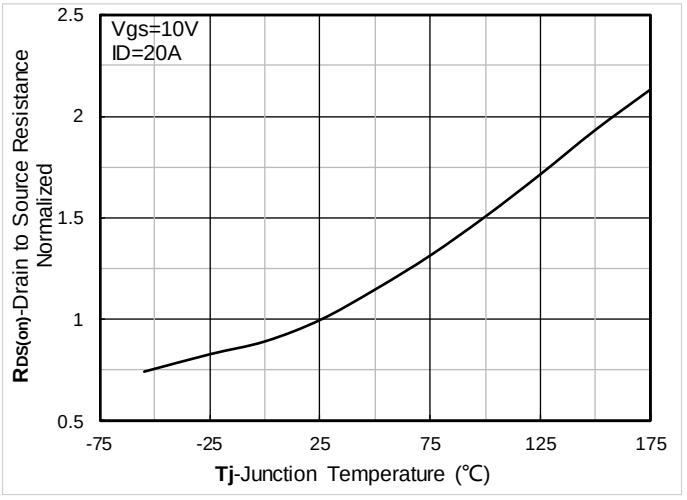



Figure 6. Normalized On-Resistance

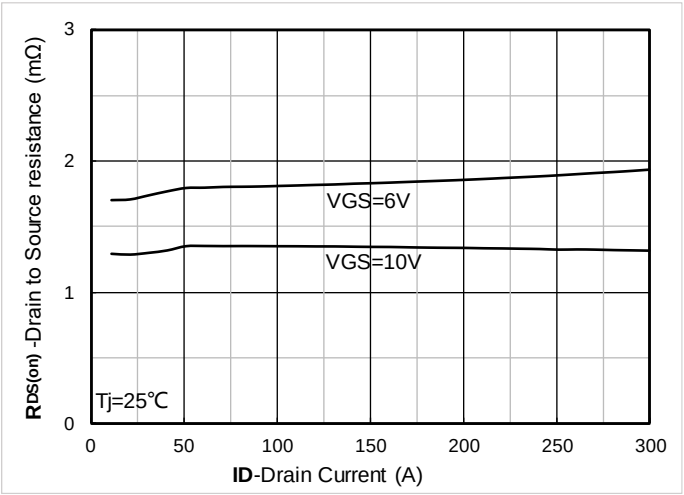



Figure 7. $R_{DS(on)}$ VS Drain Current

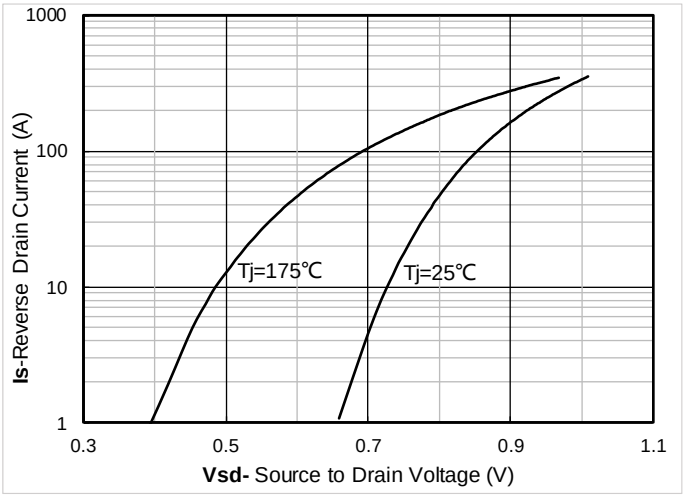



Figure 8. Forward characteristics of reverse diode

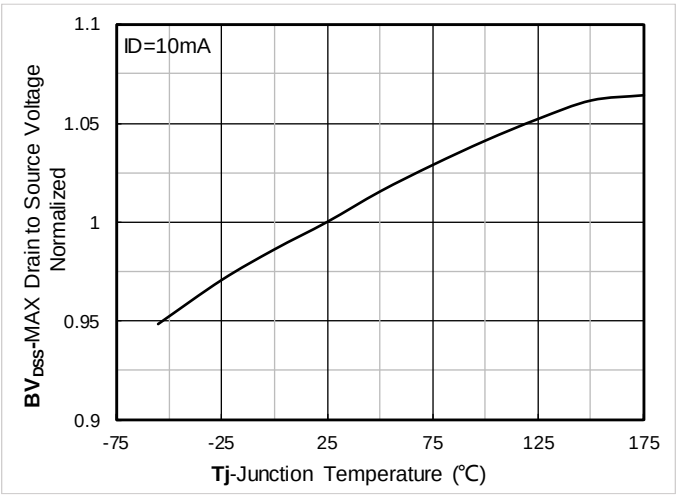



Figure 9. Normalized breakdown voltage

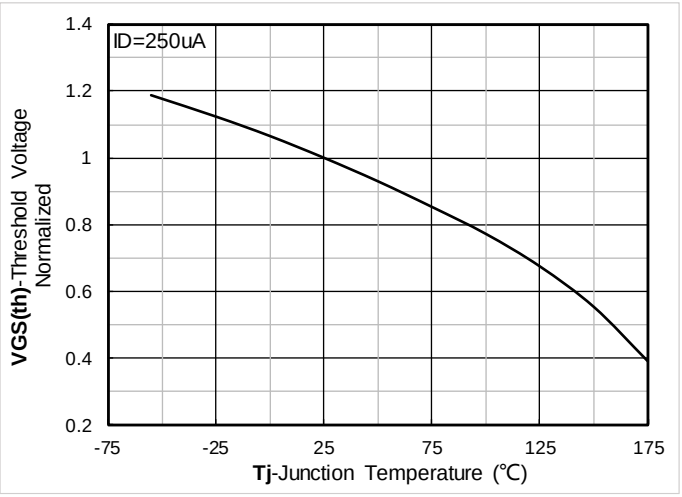



Figure 10. Normalized Threshold voltage

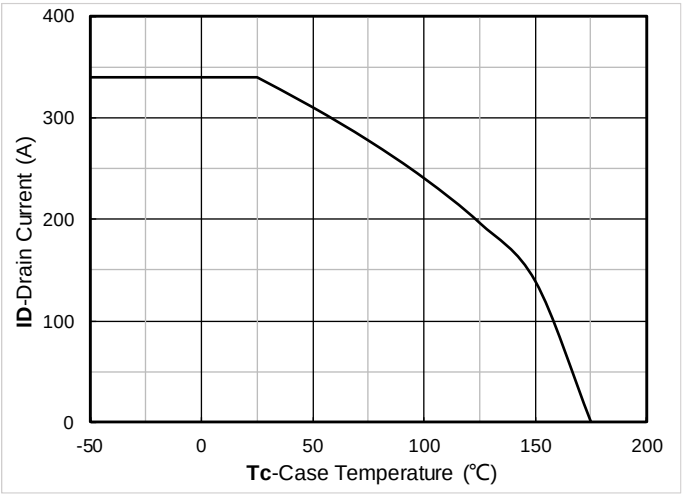



Figure 11. Current dissipation

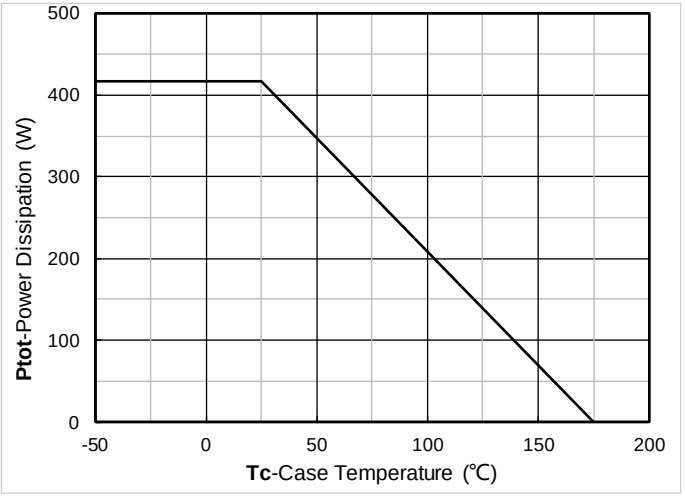



Figure 12. Power dissipation

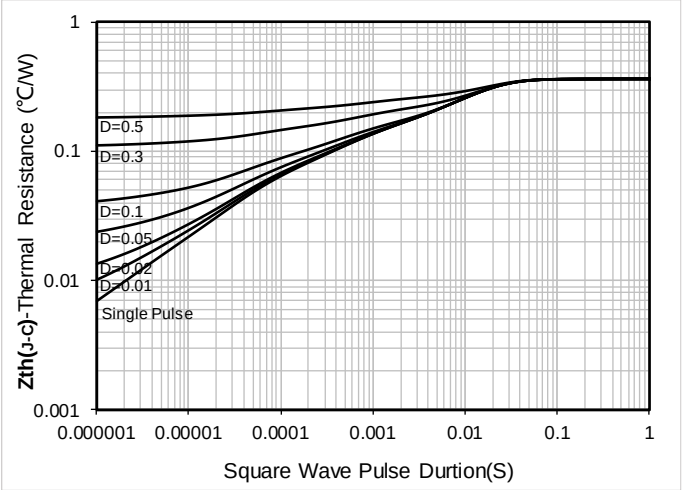



Figure 13. Maximum Transient Thermal Impedance

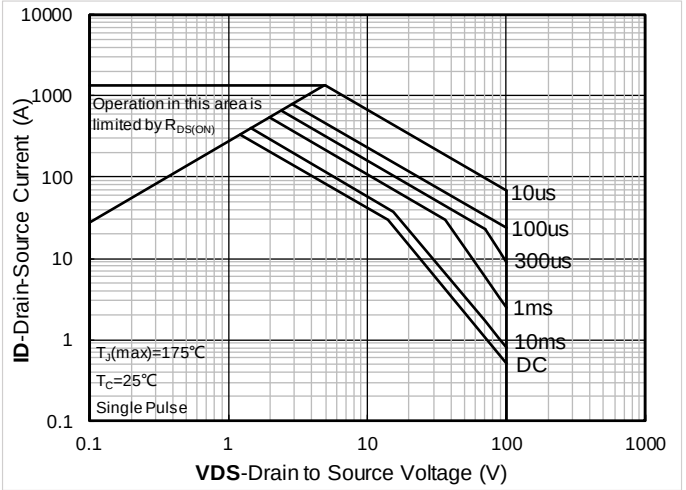



Figure 14. Safe Operation Area

## ■ Test Circuits & Waveforms

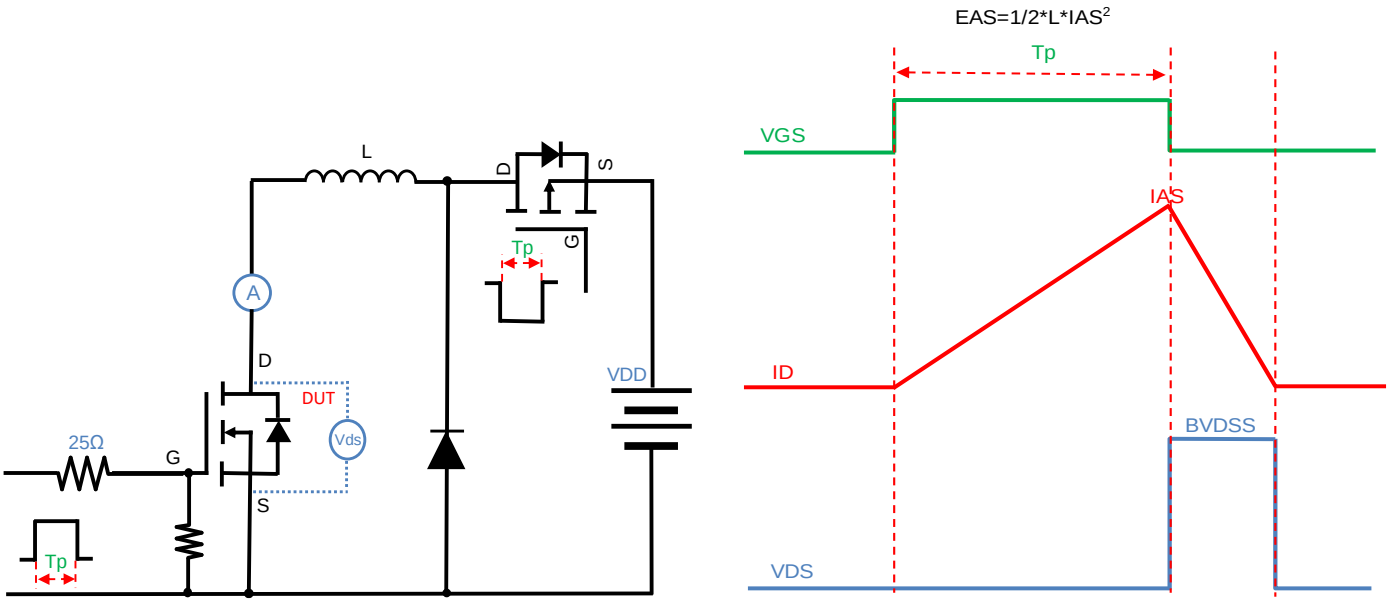



Figure A. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

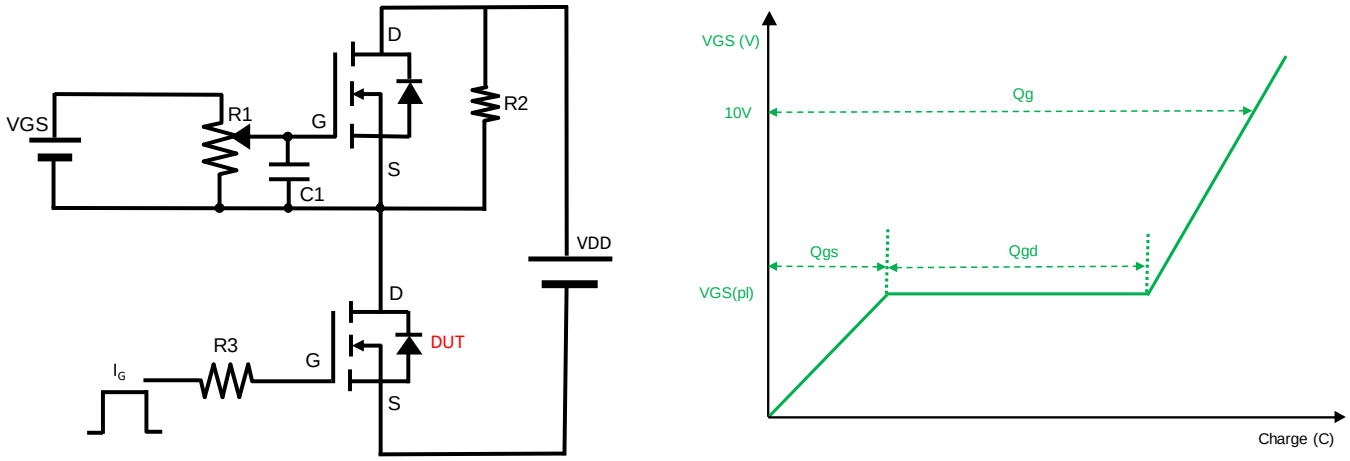



Figure B. Gate Charge Test Circuit & Waveform

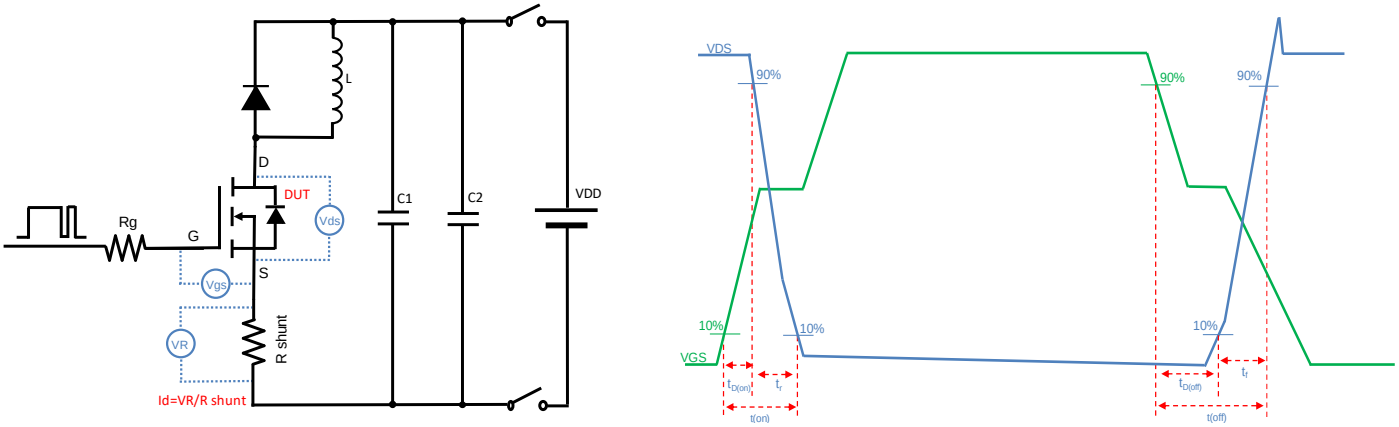



Figure C. Resistive Switching Test Circuit & Waveform

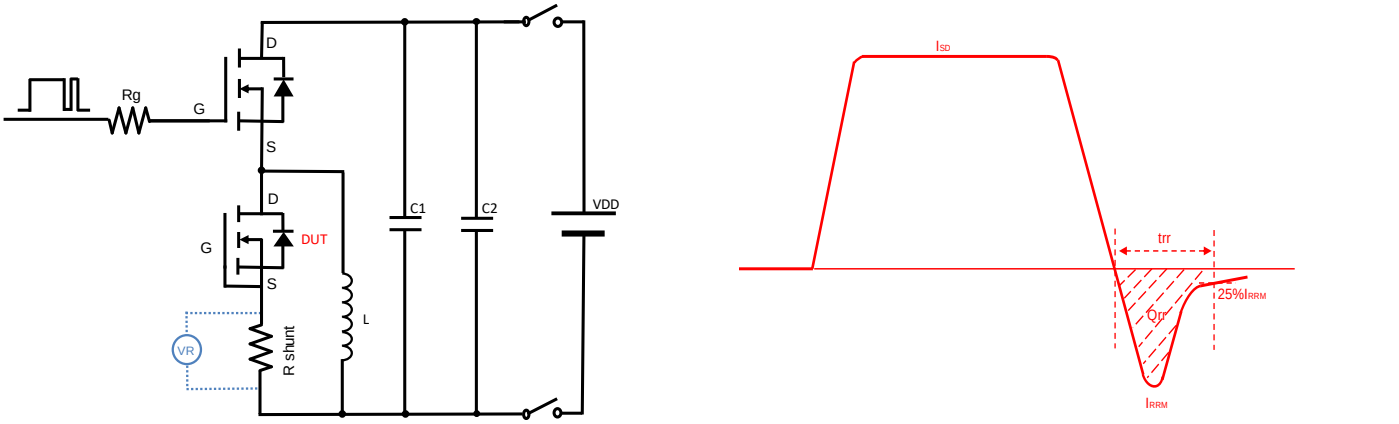
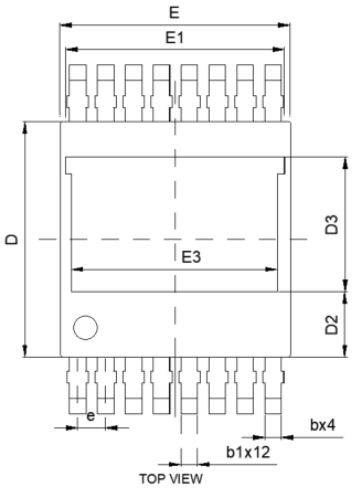
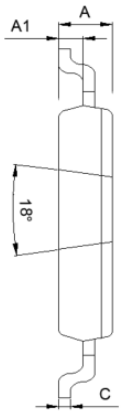



Figure D. Diode Recovery Test Circuit & Waveform

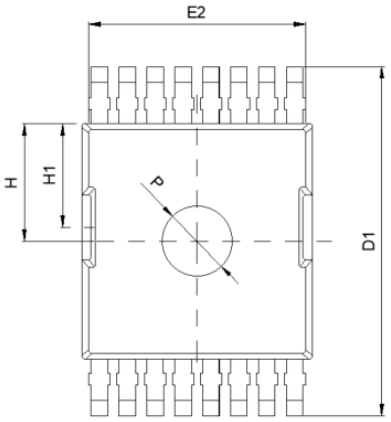
## ■ TOLT Package information



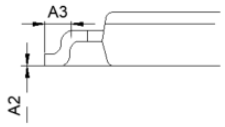
TOP VIEW

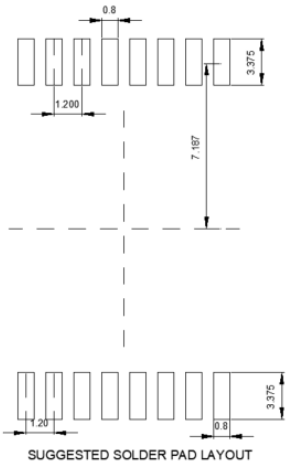


SIDE VIEW



BOTTOM VIEW



SUGGESTED SOLDER PAD LAYOUT

| DIMENSIONS | | | |
|---|---|---|---|
| SYMBOL | Millimeter | | |
| | MIN | NOM | MAX |
| A | 2.25 | 2.30 | 2.35 |
| A1 | 1.00 | 1.04 | 1.08 |
| A2 | 0.01 | 0.08 | 0.16 |
| A3 | | 1.50REF | |
| b | 0.70 | 0.75 | 0.80 |
| b1 | 0.60 | 0.70 | 0.80 |
| c | 0.40 | 0.50 | 0.60 |
| D | 10.00 | 10.10 | 10.30 |
| D1 | 14.80 | 15.00 | 15.20 |
| D2 | 2.60 | 2.80 | 3.00 |
| D3 | | 5.77REF | |
| E | 9.70 | 9.90 | 10.10 |
| E1 | | 9.46REF | |
| E2 | | 9.25REF | |
| E3 | | 8.70REF | |
| e | 1.18 | 1.20 | 1.22 |
| H | 5.00 | 5.20 | 5.40 |
| H1 | 4.40 | 4.60 | 4.80 |
| L | 2.40 | 2.45 | 2.50 |
| P | 2.80 | 3.00 | 3.20 |

NOTE:
1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
2. TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
3. THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY

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